

# MOSFET – SiC Power, Single N-Channel, TO247-4L 1200 V, 20 mΩ, 102 A

## NTH4L020N120SC1

### Features

- Typ.  $R_{DS(on)} = 20 \text{ m}\Omega$
- Ultra Low Gate Charge ( $Q_{G(\text{tot})} = 220 \text{ nC}$ )
- High Speed Switching with Low Capacitance ( $C_{oss} = 258 \text{ pF}$ )
- 100% Avalanche Tested
- $T_J = 175^\circ\text{C}$
- This Device is Pb-Free and is RoHS Compliant

### Typical Applications

- UPS
- DC/DC Converter
- Boost Inverter

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		$V_{DSS}$	1200	V	
Gate-to-Source Voltage		$V_{GS}$	-15/+25	V	
Recommended Operation Values of Gate-to-Source Voltage	$T_C < 175^\circ\text{C}$	$V_{GSop}$	-5/+20	V	
Continuous Drain Current (Note 2)	Steady State	$T_C = 25^\circ\text{C}$	$I_D$	102	A
Power Dissipation (Note 2)			$P_D$	510	W
Continuous Drain Current (Notes 1, 2)	Steady State	$T_C = 100^\circ\text{C}$	$I_D$	84	A
Power Dissipation (Notes 1, 2)			$P_D$	255	W
Pulsed Drain Current (Note 3)		$T_A = 25^\circ\text{C}$	$I_{DM}$	408	A
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to +175	°C	
Source Current (Body Diode)		$I_S$	46	A	
Single Pulse Drain-to-Source Avalanche Energy ( $I_{L(pk)} = 23 \text{ A}$ , $L = 1 \text{ mH}$ ) (Note 4)		$E_{AS}$	264	mJ	
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)		$T_L$	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

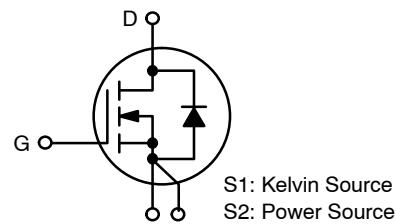
1. JA is constant value to follow guide table of LV/HV discrete final datasheet generation.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. Repetitive rating, limited by max junction temperature.
4. EAS of 264 mJ is based on starting  $T_J = 25^\circ\text{C}$ ;  $L = 1 \text{ mH}$ ,  $I_{AS} = 23 \text{ A}$ ,  $V_{DD} = 120 \text{ V}$ ,  $V_{GS} = 18 \text{ V}$ .



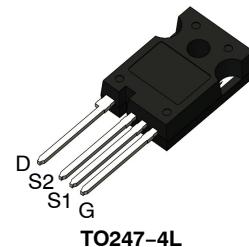
ON Semiconductor®

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$V_{(BR)DSS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
1200 V	28 mΩ @ 20 V	102 A



N-CHANNEL MOSFET



MARKING DIAGRAM



A = Assembly Location  
 Y = Year  
 WW = Work Week  
 ZZ = Lot Traceability  
 NTH4L020N120SC1 = Specific Device Code

### ORDERING INFORMATION

Device	Package	Shipping
NTH4L020N120SC1	TO247-4L	30 ea / Tube

# NTH4L020N120SC1

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case – Steady State (Note 2)	$R_{\theta JC}$	0.3	$^{\circ}\text{C}/\text{W}$
Junction-to-Ambient – Steady State (Notes 1, 2)	$R_{\theta JA}$	40	

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}$ , $I_D = 1 \text{ mA}$	1200	–	–	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(\text{BR})\text{DSS}/T_J}$	$I_D = 1 \text{ mA}$ , referenced to $25^{\circ}\text{C}$	–	0.5	–	$\text{V}/^{\circ}\text{C}$
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}$ , $V_{\text{DS}} = 1200 \text{ V}$	–	–	100	$\mu\text{A}$
		$T_J = 175^{\circ}\text{C}$	–	–	1	$\text{mA}$
Gate-to-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}} = +25/-15 \text{ V}$ , $V_{\text{DS}} = 0 \text{ V}$	–	–	$\pm 1$	$\mu\text{A}$

### ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{GS}} = V_{\text{DS}}$ , $I_D = 20 \text{ mA}$	1.8	2.7	4.3	V
Recommended Gate Voltage	$V_{\text{GOP}}$		–5	–	+20	V
Drain-to-Source On Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 20 \text{ V}$ , $I_D = 60 \text{ A}$ , $T_J = 25^{\circ}\text{C}$	–	20	28	$\text{m}\Omega$
		$V_{\text{GS}} = 20 \text{ V}$ , $I_D = 60 \text{ A}$ , $T_J = 175^{\circ}\text{C}$	–	37	50	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 20 \text{ V}$ , $I_D = 60 \text{ A}$	–	3.6	–	S

### CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	$C_{\text{ISS}}$	$V_{\text{GS}} = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $V_{\text{DS}} = 800 \text{ V}$	–	2943	–	$\text{pF}$
Output Capacitance	$C_{\text{OSS}}$		–	258	–	
Reverse Transfer Capacitance	$C_{\text{RSS}}$		–	24	–	
Total Gate Charge	$Q_{\text{G}(\text{TOT})}$	$V_{\text{GS}} = -5/20 \text{ V}$ , $V_{\text{DS}} = 600 \text{ V}$ , $I_D = 80 \text{ A}$	–	220	–	$\text{nC}$
Threshold Gate Charge	$Q_{\text{G}(\text{TH})}$		–	33	–	
Gate-to-Source Charge	$Q_{\text{GS}}$		–	66	–	
Gate-to-Drain Charge	$Q_{\text{GD}}$		–	63	–	
Gate-Resistance	$R_G$	$f = 1 \text{ MHz}$	–	1.6	–	$\Omega$

### SWITCHING CHARACTERISTICS, $V_{\text{GS}} = 10 \text{ V}$

Turn-On Delay Time	$t_{\text{d}(\text{ON})}$	$V_{\text{GS}} = -5/20 \text{ V}$ , $V_{\text{DS}} = 800 \text{ V}$ , $I_D = 80 \text{ A}$ , $R_G = 2 \Omega$ inductive load	–	21.6	35	$\text{ns}$
Rise Time	$t_r$		–	21	34	
Turn-Off Delay Time	$t_{\text{d}(\text{OFF})}$		–	41	66	
Fall Time	$t_f$		–	10	20	
Turn-On Switching Loss	$E_{\text{ON}}$		–	494	–	
Turn-Off Switching Loss	$E_{\text{OFF}}$	$V_{\text{GS}} = -5/20 \text{ V}$ , $I_{\text{SD}} = 80 \text{ A}$ , $dI_{\text{SD}}/dt = 1000 \text{ A}/\mu\text{s}$	–	397	–	$\mu\text{J}$
Total Switching Loss	$E_{\text{tot}}$		–	891	–	

### DRAIN-SOURCE DIODE CHARACTERISTICS

Continuous Drain-Source Diode Forward Current	$I_{\text{SD}}$	$V_{\text{GS}} = -5 \text{ V}$ , $T_J = 25^{\circ}\text{C}$	–	–	46	$\text{A}$
Pulsed Drain-Source Diode Forward Current (Note 3)	$I_{\text{SDM}}$		–	–	408	
Forward Diode Voltage	$V_{\text{SD}}$	$V_{\text{GS}} = -5 \text{ V}$ , $I_{\text{SD}} = 30 \text{ A}$ , $T_J = 25^{\circ}\text{C}$	–	3.7	–	$\text{V}$
Reverse Recovery Time	$t_{\text{RR}}$		–	30	–	
Reverse Recovery Charge	$Q_{\text{RR}}$	$V_{\text{GS}} = -5/20 \text{ V}$ , $I_{\text{SD}} = 80 \text{ A}$ , $dI_{\text{SD}}/dt = 1000 \text{ A}/\mu\text{s}$	–	225	–	$\text{nC}$
			–	–	–	

# NTH4L020N120SC1

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Reverse Recovery Energy	E <sub>REC</sub>	V <sub>GS</sub> = -5/20 V, I <sub>SD</sub> = 80 A, dI <sub>S</sub> /dt = 1000 A/μs	–	16	–	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		–	15	–	A
Charge time	T <sub>a</sub>		–	16	–	ns
Discharge time	T <sub>b</sub>		–	15	–	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## TYPICAL CHARACTERISTICS

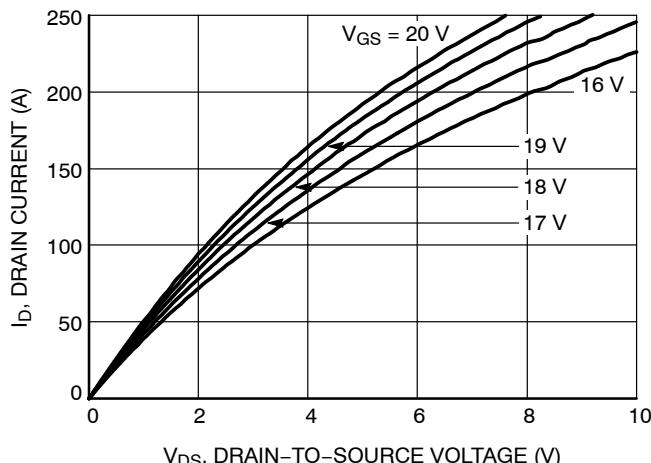


Figure 1. On-Region Characteristics

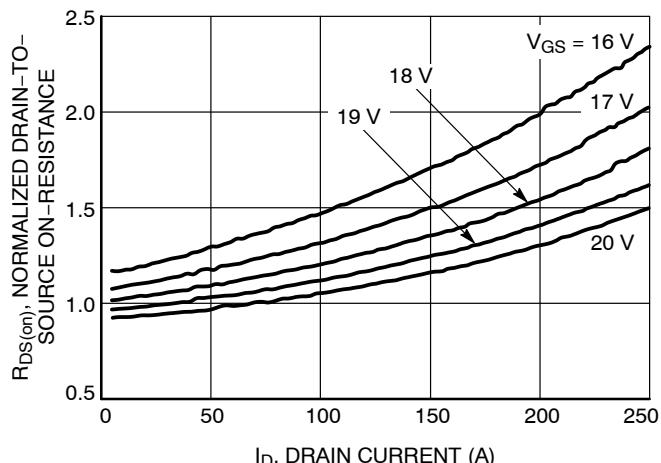


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

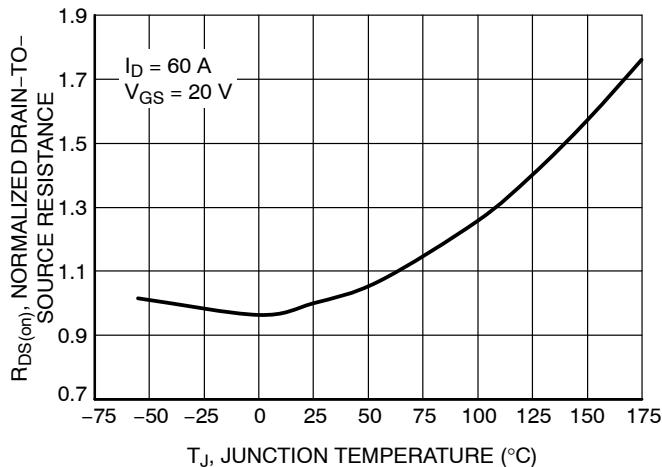


Figure 3. On-Resistance Variation with Temperature

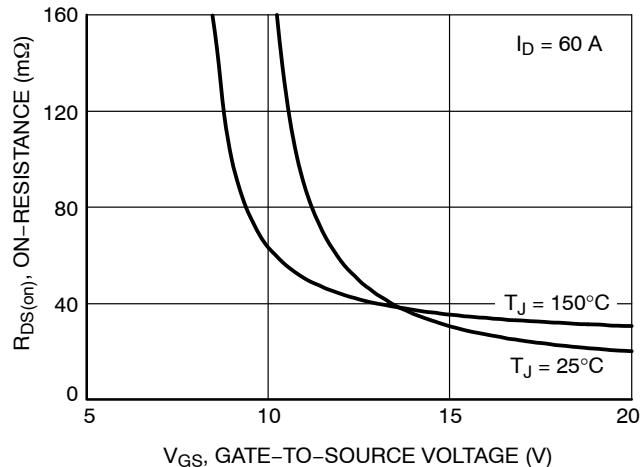


Figure 4. On-Resistance vs. Gate-to-Source Voltage

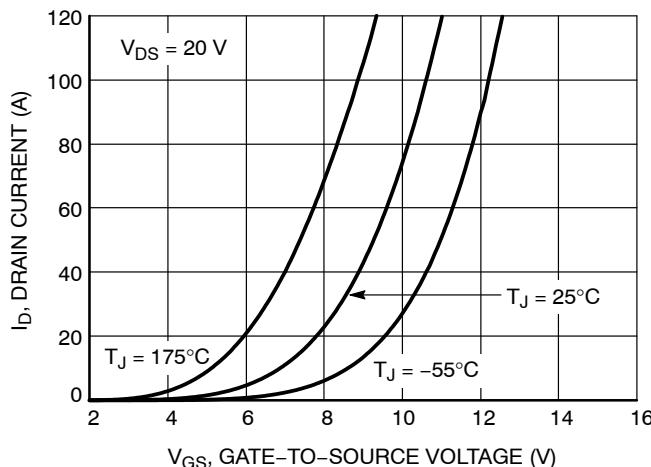


Figure 5. Transfer Characteristics

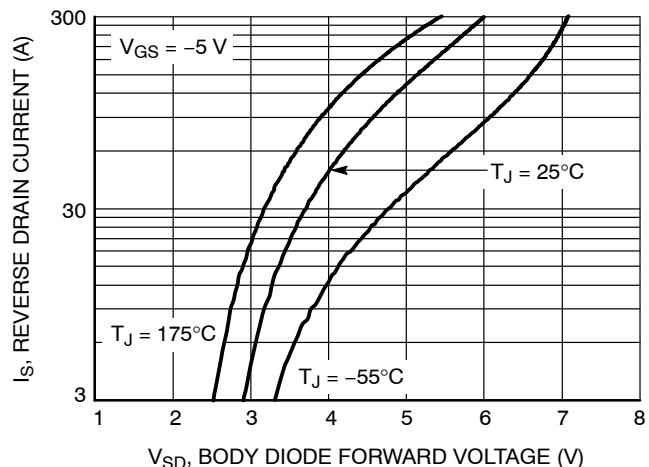


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS

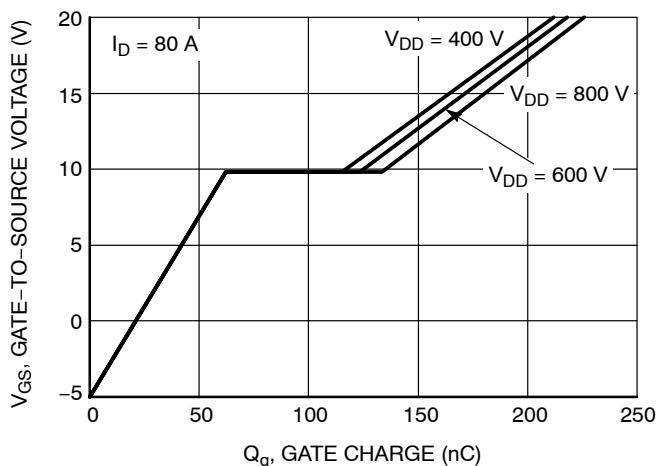


Figure 7. Gate-to-Source Voltage vs. Total Charge

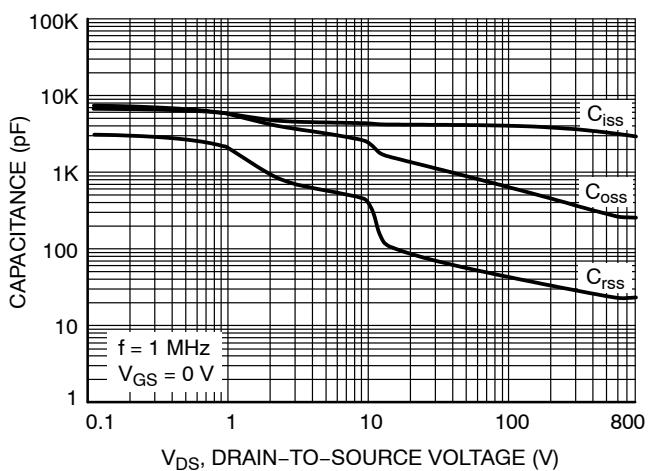


Figure 8. Capacitance vs. Drain-to-Source Voltage

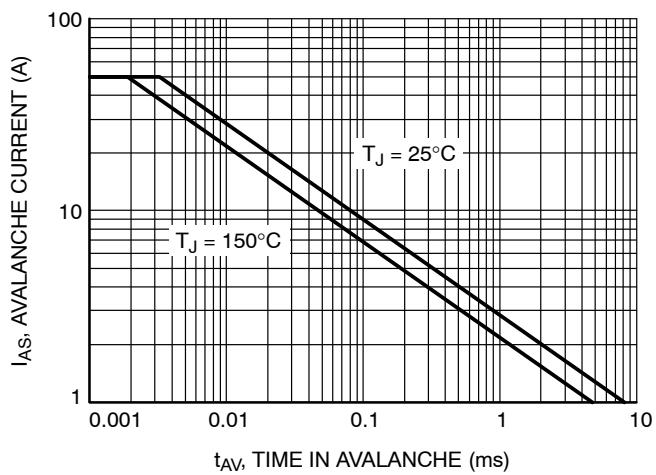


Figure 9. Unclamped Inductive Switching Capability

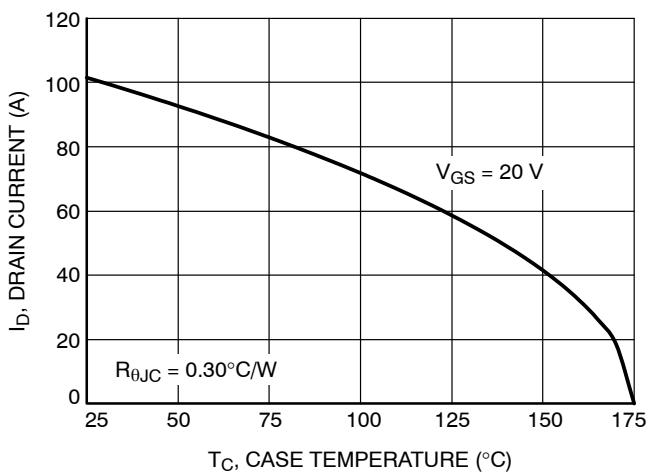


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

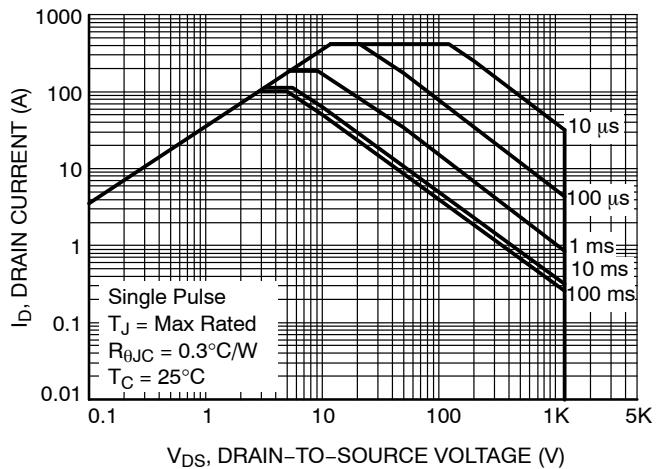


Figure 11. Safe Operating Area

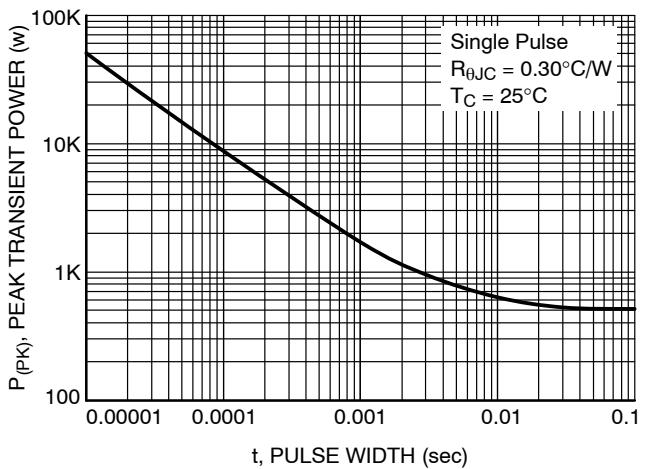


Figure 12. Single Pulse Maximum Power Dissipation

## TYPICAL CHARACTERISTICS

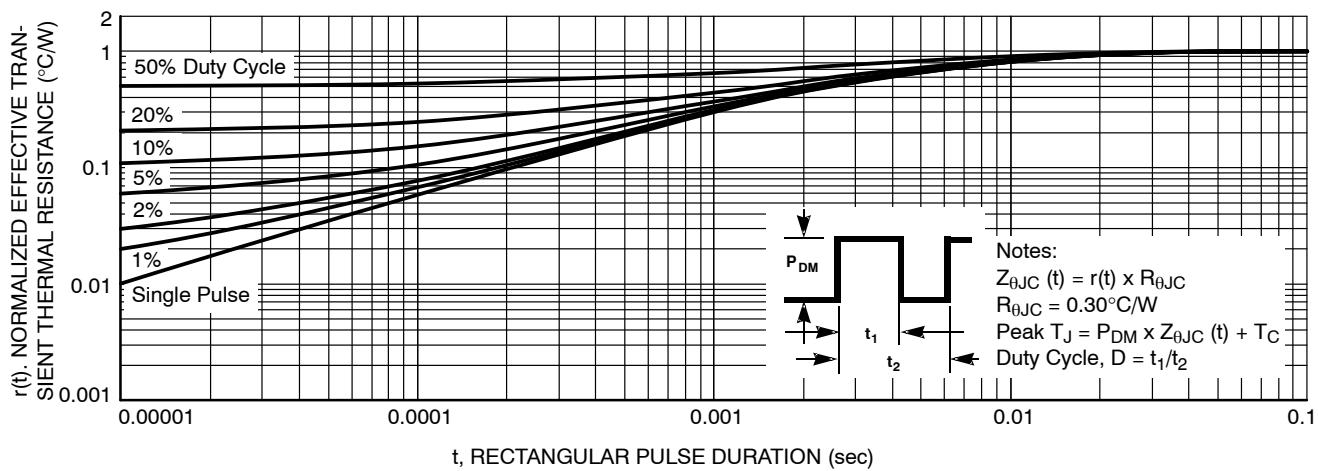
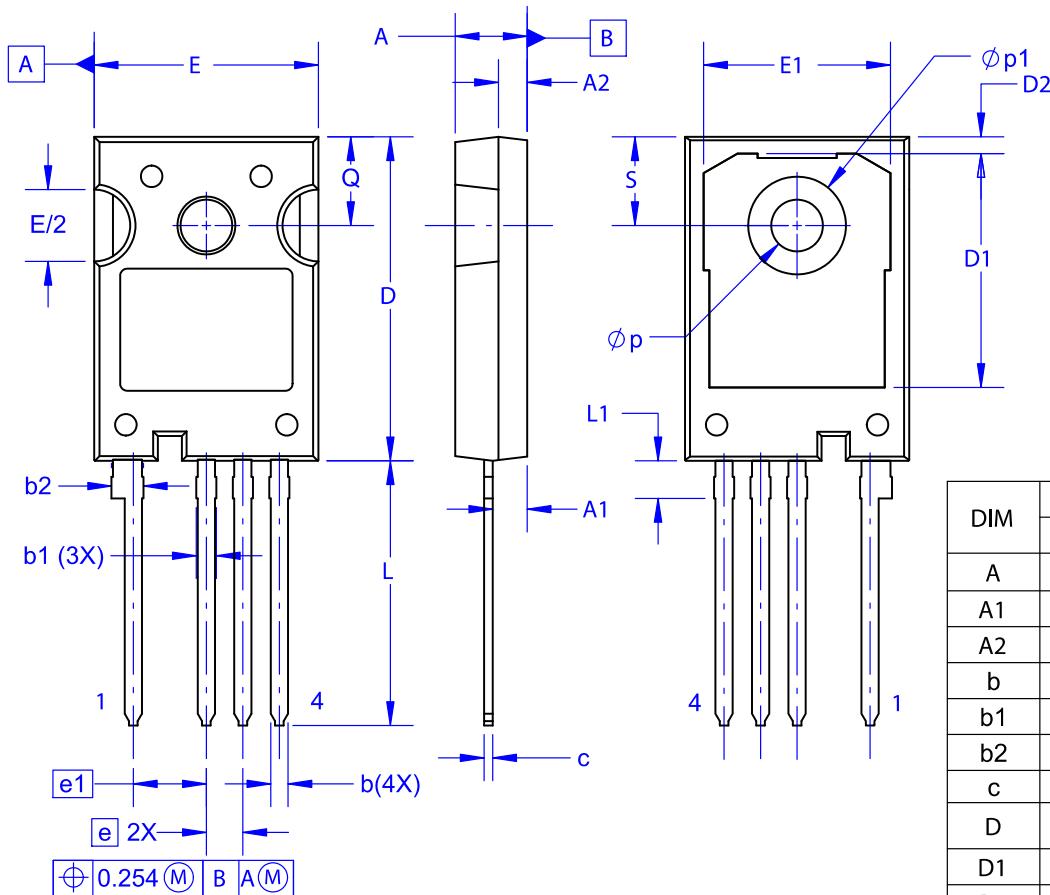


Figure 13. Junction-to-Ambient Thermal Response

TO-247-4LD  
CASE 340CJ  
ISSUE A

DATE 16 SEP 2019



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b1	1.20	1.40	1.60
b2	2.02	2.22	2.42
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.25	16.50
D2	0.97	1.17	1.37
e	2.54 BSC		
e1	5.08 BSC		
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E/2	4.80	5.00	5.20
L	18.22	18.42	18.62
L1	2.42	2.62	2.82
p	3.40	3.60	3.80
p1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

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